

**LTM8062 77LD 15mm X 9mm X 4.32mm Epoxy (DA) (TABLE OF MATERIAL DECLARATION)**
*The LTM8062 is RoHS compliant per EU RoHS Directive 2003/95/EC.*

It contains less than 100ppm cadmium (Cd) and less than 1,000ppm of each - lead (Pb), mercury (Hg), hexavalent chromium (Cr+), polybrominated biphenyl (PBB) and polybrominated diphenyl ether (PBDE)

No.	Part Name	Material Name	Component Weight (gram)	Materials Analysis (element)	CAS Number	Material Mass (gram)	Materials Analysis (weight %)
1	Substrate	Circuit Board	0.1399	Barium Compounds	7727-43-7	0.00378	2.70
				BT Resin/Filler (Silica Crystalline)	105391-33-1, 1156-51-0/9003-36-5/21645-51-2	0.05053	36.12
				Copper Metal	7440-50-8	0.03484	24.90
				Copper Compounds	147-14-8	0.00003	0.02
				Ecotoxic substances	7440-38-2, 7440-28-0	0.00000	0.00
				Gold metal or alloy	7440-57-5	0.00046	0.33
				Nickel	7440-02-0	0.00213	1.52
				Zinc	7440-66-6	0.00004	0.03
				Continuous Filament Fiber Glass	65997-17-3	0.03970	28.38
				Acrylic Resin	non-disclosure	0.00719	5.14
				Epoxy Resin	non-disclosure	0.00003	0.02
				Chromium(III) Oxide	1308-38-9	0.00000	0.00
				Silica amorphous	7631-86-9	0.00008	0.06
				Talc;not containing fibers like asbestos	14807-96-9	0.00043	0.31
				Aromatic Carbonyl compounds	non-disclosure	0.00041	0.29
				Cyanoguanidine	461-58-5	0.00001	0.01
				Calcium caobonate	471-34-1	0.00001	0.00
				Amine compounds	non-disclosure	0.00005	0.04
				Leveling agent and others	non-disclosure	0.00017	0.12
2	Solder Paste	Alloy	0.0017	Sn	7440-31-5	0.00160	95.00
				Sb	7440-36-0	0.00008	5.00
3	Epoxy		0.0012	Di-ester resin	non-disclosure	0.00012	10.00
				Functionalized ester	non-disclosure	0.00012	10.00
				Silver	7440-22-4	0.00096	80.00
4	Passive/Active Components		0.7177	Iron Powder (Fe)	7439-89-6	0.43297	60.32
				Copper (Cu)	7440-50-8	0.25202	35.11
				Nickel (Ni)	7440-02-0	0.00535	0.75
				Tin (Sn)	7440-31-5	0.00202	0.28
				Ceramic (Ba Compounds)	12047-27-7	0.02541	3.54
5	Active lcs	Silicon	0.0033	Silicon	7440-21-3	0.00325	100.00
6	Wire	Gold	0.0155	Au	7440-57-5	0.01550	99.99
7	Encapsulation	Epoxy Resin	0.8186	Fused Silica	60676-86-0	0.63193	77.20
				Epoxy Resin	non-disclosure	0.07285	8.90
				Phenol Resin	non-disclosure	0.07285	8.90
				Crytalline Silica	14808-60-7	0.02456	3.00
				Carbon Black	1333-86-4	0.00409	0.50
				Metal Hydroxide	non-disclosure	0.01228	1.50
Total Package Weight			1.6979				

Note: Composition derived from MSDS and material C of C from Vendors;Component Weight based on assembly of generic parts